HALOGEN

FREE



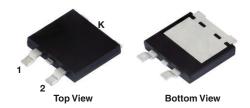
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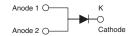
Vishay General Semiconductor

TMBS® (Trench MOS Barrier Schottky) Rectifier for PV Solar Cell Bypass Protection

Ultra Low $V_F = 0.31 \text{ V}$ at $I_F = 5 \text{ A}$

eSMP[®] Series SMPD (TO-263AC)





LINKS TO ADDITIONAL RESOURCES



| PRIMARY CHARACTERISTICS | | | | |
|--|-----------------|--|--|--|
| I _{F(AV)} | 20 A | | | |
| V_{RRM} | 45 V | | | |
| I _{FSM} | 160 A | | | |
| V_F at $I_F = 20$ A $(T_A = 125 ^{\circ}C)$ | 0.50 V | | | |
| T _{OP} max. (AC model) | 150 °C | | | |
| T _J max. (DC forward current) | 200 °C | | | |
| Package | SMPD (TO-263AC) | | | |
| Circuit configuration | Single | | | |

FEATURES

- Trench MOS Schottky technology
- Very low profile typical height of 1.7 mm
- · Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

For use in solar cell junction box as a bypass diode for protection, using DC forward current without reverse bias.

MECHANICAL DATA

Case: SMPD (TO-263AC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Terminals: matte tin plated leads, solderable per

J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

| MAXIMUM RATINGS (T _A = 25 °C unless otherwise noted) | | | | | |
|--|-------------------------------|-------------|------|--|--|
| PARAMETER | SYMBOL | V20DL45BP | UNIT | | |
| Maximum repetitive peak reverse voltage | V_{RRM} | 45 | V | | |
| Maximum DC forward current (fig. 1) | I _{F(DC)} (1) | 20 | А | | |
| Peak forward surge current 10 ms single half sine-wave superimposed on rated load | I _{FSM} | 160 | А | | |
| Operating junction temperature range (AC model) | T _{OP} | -40 to +150 | °C | | |
| Junction temperature in DC forward current without reverse bias, $t = \le 1 \text{ h}$ | T _J ⁽²⁾ | ≤ 200 | °C | | |

Note

- (1) With heatsink
- (2) Meets the requirements of IEC 61215 ed.2 bypass diode thermal test



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| ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted) | | | | | | |
|---|-----------------------|-------------------------|---------------------------------|------|------|------|
| PARAMETER | TEST CO | TEST CONDITIONS | | TYP. | MAX. | UNIT |
| Instantaneous forward voltage | I _F = 5 A | T _A = 25 °C | V _F ⁽¹⁾ | 0.42 | - | V |
| | I _F = 10 A | | | 0.48 | - | |
| | I _F = 20 A | | | 0.55 | 0.64 | |
| | I _F = 5 A | T _A = 125 °C | | 0.31 | - | |
| | I _F = 10 A | | | 0.38 | - | |
| | I _F = 20 A | | | 0.50 | 0.58 | |
| Reverse current | V _R = 45 V | T _A = 25 °C | - I _R ⁽²⁾ | - | 2.5 | - mA |
| | v _R = 45 v | T _A = 125 °C | | 20 | 50 | |

Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 5 ms

| THERMAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted) | | | | |
|---|-------------------------|-----------|------|--|
| PARAMETER | SYMBOL | V20DL45BP | UNIT | |
| Typical thermal resistance | $R_{	heta JC}$ | 1.6 | °C/W | |
| | R _{0JA} (1)(2) | 45 | | |

Notes

 $^{(1)}$ The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$

(2) Free air, without heatsink

| ORDERING INFORMATION (Example) | | | | | |
|--------------------------------|----------------|-----------------|--------------|---------------|------------------------------------|
| PACKAGE | PREFERRED P/N | UNIT WEIGHT (g) | PACKAGE CODE | BASE QUANTITY | DELIVERY MODE |
| SMPD (TO-263AC) | V20DL45BP-M3/I | 0.55 | 1 | 2000/reel | 13" diameter plastic tape and reel |

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25$ °C unless otherwise noted)

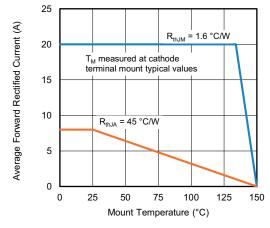


Fig. 1 - Forward Current Derating Curve

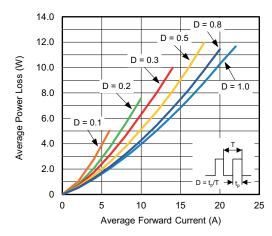


Fig. 2 - Forward Power Loss Characteristics



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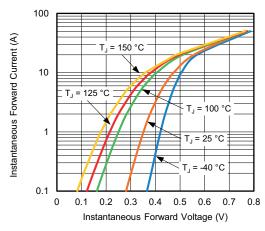


Fig. 3 - Typical Instantaneous Forward Characteristics

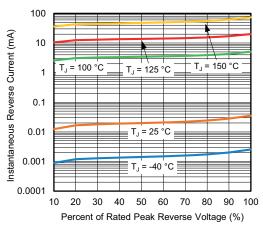


Fig. 4 - Typical Reverse Characteristics

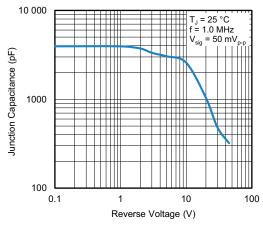


Fig. 5 - Typical Junction Capacitance

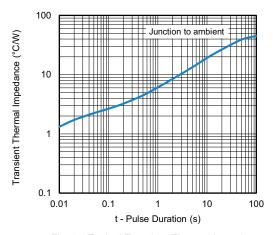


Fig. 6 - Typical Transient Thermal Impedance

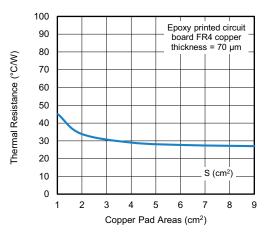
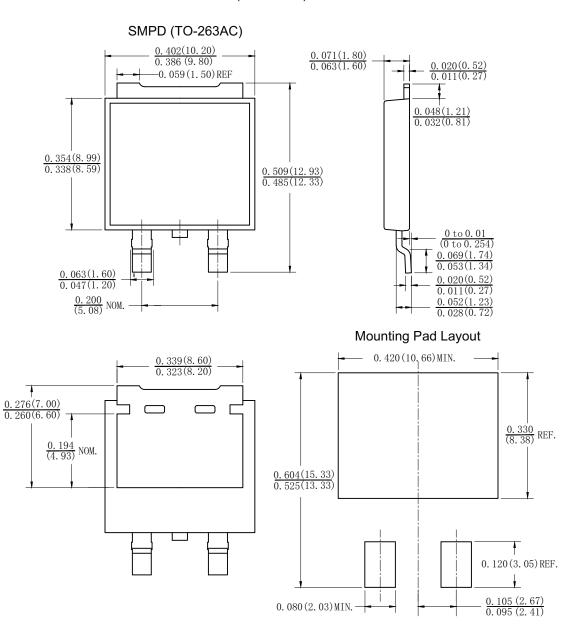


Fig. 7 - Thermal Resistance Junction-to-Ambient vs. Copper Pad Areas



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PACKAGE OUTLINE DIMENSIONS in inches (millimeters)





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